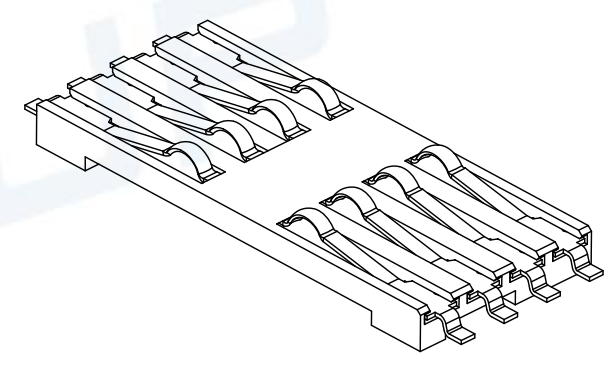
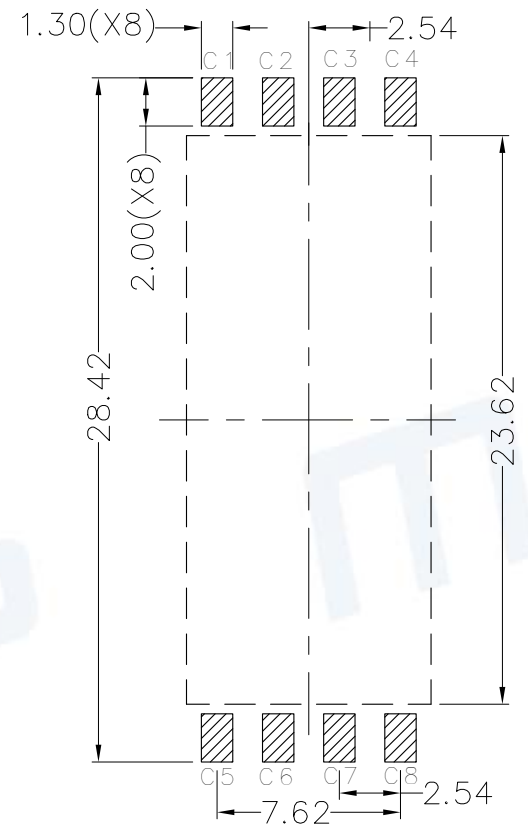
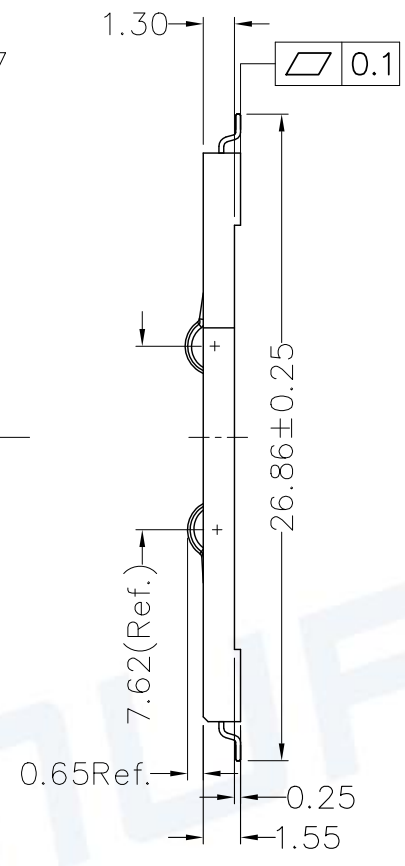
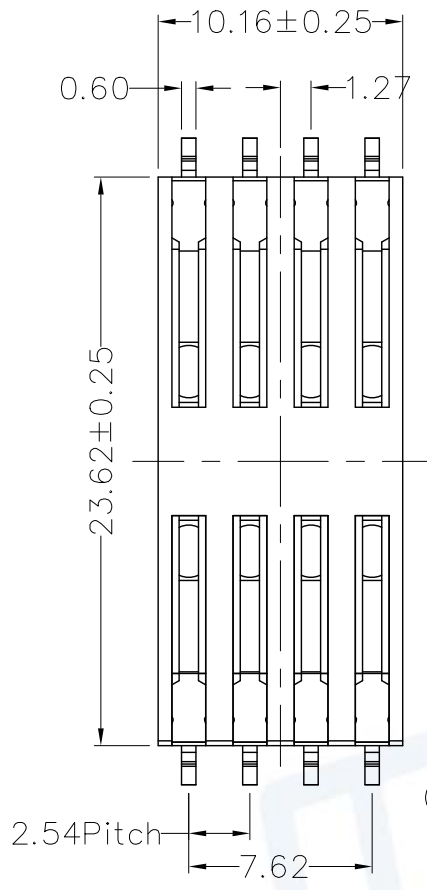


REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1					
X2					



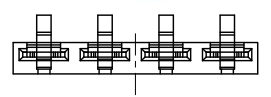
RECOMMENDED P.C.B LAYOUT

COMPONENT SIDE(TOLERANCE ±0.05)

Coplanarity of metal solder pins $\leq 0.15\text{mm}$
 Recommending of solder paste thickness >0.15mm

TECHNICAL CHARACTERISTICS

- General Characteristics
 Dimensions: 23.62Lx10.16WxHmm
 Weight: Approx.0.50±0.1g
 Durability: 100,000 cycles min.
- Electrical Characteristics
 Contact resistance: 50mΩ typical, 100mΩ max
 Insulation resistance: >1000MΩ/500V DC
- Solderability
 Vapor phase: 215°C, 30sec. Max
 IR reflow: 250°C, 5sec. Max
 Manual soldering: 370°C, 3sec. Max
- Environmental Characteristics
 Operating temperature: -40°C~+85°C
 Operating humidity: 10%~+95%RH



ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	BASE	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	8	Copper Alloy	Contact area: Gold plated

Unless otherwise specified, other tolerance are:

MUP MUP INDUSTRIAL CO.,LTD.

NAME: **Smart Card Connector**

MODEL NO: **MUP-C739-3**

TYPE: **w/o post H1.55**

PROJ.	UNIT	SCALE	DRAWN	Zoey Sep.15.2009	DWG NO.:	DWG-MUP-C739-3
	MM	1:1	CHECKED	Jay Sep.15.2009	SHEET	1/1
CUSTOMER DRAWING			APPROVAL	Simon Sep.15.2009	REVISION	X1

